

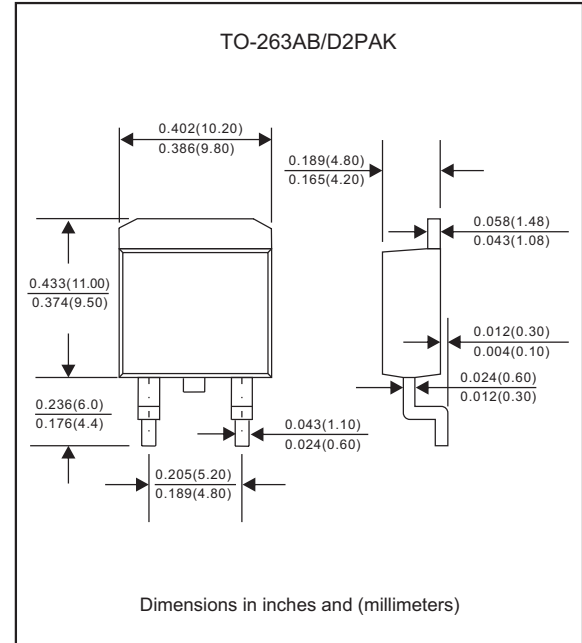
Features

- Batch process design, excellent power dissipation offers better reverse leakage current and thermal resistance.
- Low power loss, high efficiency.
- High current capability, low forward voltage drop.
- High surge capability.
- Guardring for overvoltage protection.
- Ultra high-speed switching.
- Silicon epitaxial planar chip, metal silicon junction.
- Lead-free parts meet environmental standards of MIL-STD-19500 /228
- Compliant to Halogen-free
- Suffix "-Q1" for AEC-Q101

Mechanical data

- Epoxy:UL94-V0 rated flame retardant
- Case : Molded plastic, TO-263AB / D2PAK
- Terminals : Solder plated, solderable per MIL-STD-750, Method 2026
- Mounting Position : Any

Package outline



Maximum ratings and Electrical Characteristics (AT $T_A=25^{\circ}\text{C}$ unless otherwise noted)

PARAMETER	CONDITIONS	Symbol	MIN.	TYP.	MAX.	UNIT
Forward rectified current	See Fig.1	I_O			40.0	A
Forward surge current	8.3ms single half sine-wave (JEDEC methode)	I_{FSM}			200	A
Reverse current	$V_R = V_{RRM} \quad T_J = 25^{\circ}\text{C}$	I_R			0.1	mA
	$V_R = V_{RRM} \quad T_J = 125^{\circ}\text{C}$				20	
Thermal resistance (1)	Junction to case	$R_{\theta JC}$		3		$^{\circ}\text{C/W}$
Storage temperature		T_{STG}	-65		+175	$^{\circ}\text{C}$

NOTE : (1) Device mounted on additional heatsink, (50mm x 50mm x 23mm Al heatsink).

SYMBOLS	V _{RRM} ^{*1} (V)	V _{RMS} ^{*2} (V)	V _R ^{*3} (V)	V _F ^{*4} (V)	Operating temperature T _J , (°C)
MBR4040CG-Q1	40	28	40	0.70	-55 to +150
MBR4045CG-Q1	45	31.5	45		
MBR4050CG-Q1	50	35	50	0.80	
MBR4060CG-Q1	60	42	60		
MBR4080CG-Q1	80	56	80	0.88	
MBR40100CG-Q1	100	70	100		
MBR40150CG-Q1	150	105	150	0.92	-55 to +175
MBR40200CG-Q1	200	140	200		

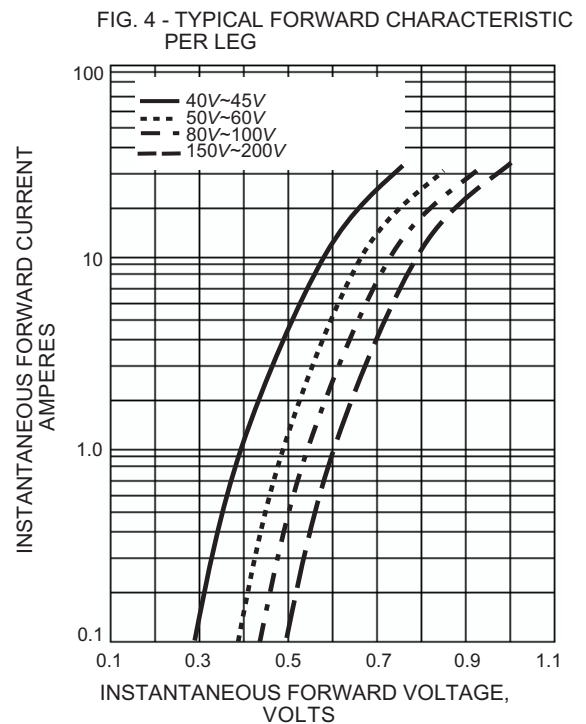
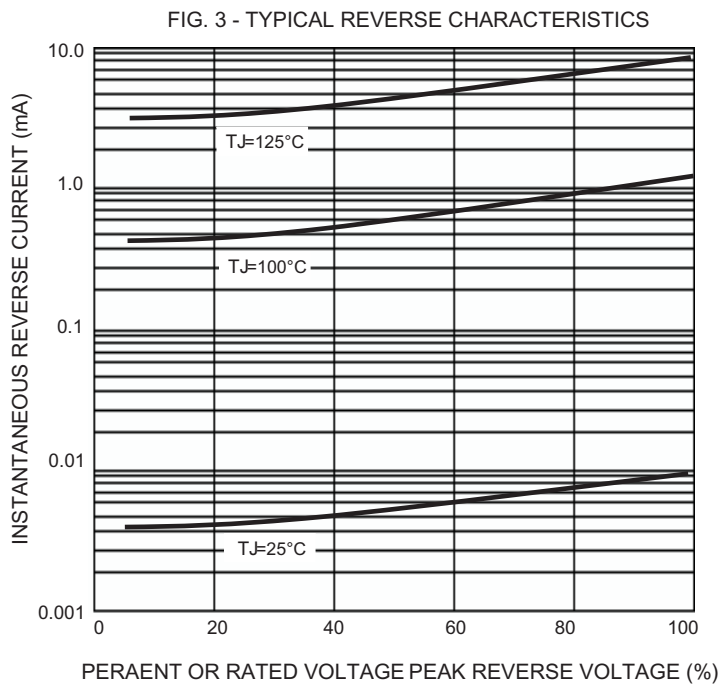
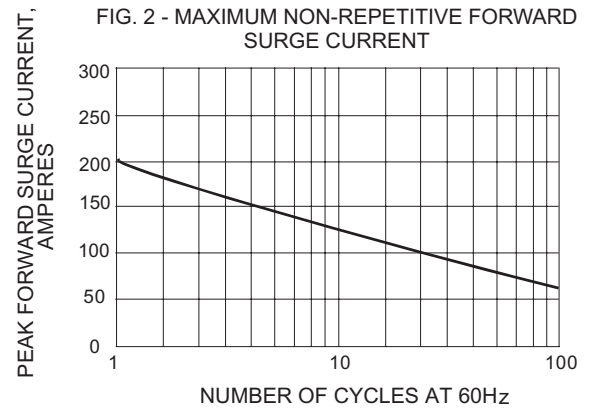
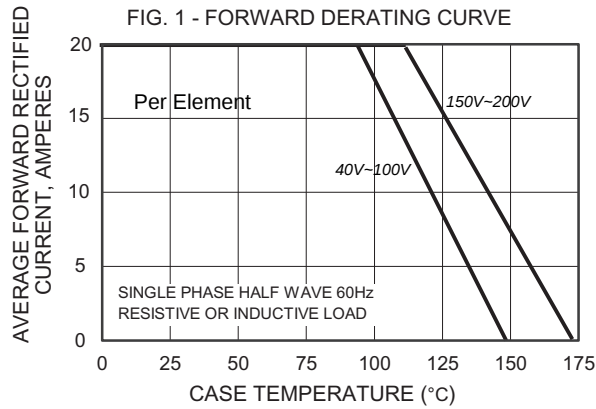
*1 Repetitive peak reverse voltage

*2 RMS voltage

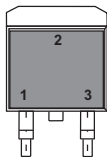
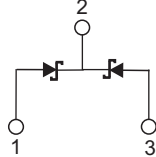
*3 Continuous reverse voltage

*4 Maximum forward voltage
 $I_F = 20.0\text{A}, 25^{\circ}\text{C}$

Rating and characteristic curves



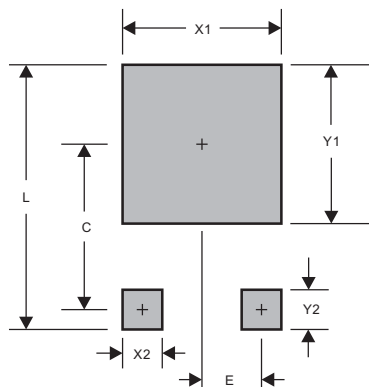
Pinning information

Pin	Simplified outline	Symbol
Pin1 anode Pin2 cathode Pin3 anode		

Marking

Type number	Marking code
MBR4040CG-Q1	MBR4040CG
MBR4045CG-Q1	MBR4045CG
MBR4050CG-Q1	MBR4050CG
MBR4060CG-Q1	MBR4060CG
MBR4080CG-Q1	MBR4080CG
MBR40100CG-Q1	MBR40100CG
MBR40150CG-Q1	MBR40150CG
MBR40200CG-Q1	MBR40200CG

Suggested solder pad layout



PACKAGE	D2PAK
C	0.374(9.50)
E	0.098(2.50)
L	0.665(16.90)
X1	0.425(10.80)
X2	0.071(1.80)
Y1	0.449(11.40)
Y2	0.138(3.50)

Dimensions in inches and (millimeters)